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SESSION: Advanced Packaging I
Time: 13:10-15:10, Wednesday, Oct. 26, 2022
Chair: Chih Hang Tung, TSMC
Tz-Cheng Chiu, National Cheng Kung University

Paper Code	Topic	Lead Author	Affiliation
AS0074	A Laser Release Temporary Bonding Tape for Hybrid Bonding Having High Thermal Resistance and Excellent Thickness Uniformity...1	Izumi Daido	SEKISUI CHEMICAL CO., LTD
AS0080	Nano-Artifact Metrics Chip Mounting Technology for Edge AI Device Security...5	Hitoshi Masago	Waseda University
TW0086	Effects of Shielding Materials on EMI Performance for 5G Wi-Fi Applications...9	Shen-Yu Yang	Wistron NeWeb Corporation
AS0037	Plasma-Activated Cu-Cu/Al-Al Direct Bonding for Electronics Packaging...13	Liangxing Hu	Nanyang Technological University
TW0063	Low Thermal Budget Cu/SiO2 Hybrid Bonding Using Highly <111>-oriented Nanotwinned Cu with Low Contact Resistivity and High Bonding Strength...17	Jia Juen Ong	National Chiao Tung University

SESSION: Advanced Design, Modeling & Testing I
Time: 15:40-17:40, Wednesday, Oct. 26, 2022
Chair: Kuoming Chen, UMC
Chang-Chun Lee, National Tsing Hua University

Paper Code	**Topic**	**Lead Author**	**Affiliation**
TW0067	LAB Flip Chip Reflow Process Robustness Prediction by Thermal Simulation...21	Ching Ho Chang	AMKOR
TW0041	Thermal Performance of Single-Phase and Two-Phase Immersion Cooling in Data Center...25	Chun-Kai Liu	Industrial Technology Research Institute
TW0004	Quantified tabbed lines and ground void impact on real DDR5 eye margin...29	Dirack Lai	Intel

SESSION: Advanced Bonding and Interconnect Technology
Time: 10:00-12:00, Thursday, Oct. 27, 2022
Chair: Chih Chen, National Yang Ming Chiao Tung University
Ting-Li Yang, Mediatek

SESSION: Fan-Out and Heterogeneous Packaging
Time: 13:10-15:10, Thursday, Oct. 27, 2022
Chair: David Tarng, ASE
Shih-Kang Lin, National Cheng Kung University

Paper Code	Topic	Lead Author	Affiliation
AS0013	High Temperature Resistant Pretection Tape For Panel Level Embedded Chip Package on Substrate...46	Lei Dong	3M Company
TW0058	RF Devices Integrated by Fan-Out and System-In-Package Technology...50	Cheng-Yuan Kung	Advanced Semiconductor Engineering (ASE) Inc.
TW0071	A Study of Material Extraction and Moisture Effect on mmWave Fan-out Package Design...54	Chiung-Ying Kuo	ASE Group

SESSION: Advanced and Green Materials and Process
Time: 13:10-15:10, Thursday, Oct. 27, 2022
Chair: Vincent Wei,iCana Limited
Kuo-Chan Chiou, ITRI

Paper Code	Topic	Lead Author	Affiliation
TW0089	A Fluorinated Electronic Grade Coating which can Help to Pass ANSI/ISA G3 Corrosion Test for Protecting Outdoor Electronics...58	Dem Lee	Integrated Service Technology, Inc.
AS0024	Study on Interfacial Reaction and Tensile Properties in the C1990HP/Sn/C1990HP Sandwich Couples...64	Andromeda Laksono	National Taiwan University of Science and Technology

SESSION: Advanced Design, Modeling & Testing II
Time: 15:40-17:40, Thursday, Oct. 27, 2022
Chair: Sheng-Jye Hwang, National Cheng Kung University
Lewis Huang, Senju

Paper Code	Topic	Lead Author	Affiliation
EU0082	Raman Spectroscopy and Hyperspectral Imaging for Wafer-On-Wafer (WOW) Processing...68	Anton Myalitsin	ANVOS Analytics Co., Ltd.
AS0097	System Level IR Drop Impact on Chip Power Performance Signoff for RISC-V System on Chip...72	kin fei yong	starfive
TW0103	DDR Debug Methodology for Board Design Quality and System Robustness...76	Thonas Su	Intel
TW0040	A Novel Modelling Methodology for Underfill Molding Process On 2.2D Heterogeneous Integrated Substrate...80	Yu-En Liang	CoreTech Moldex3D
TW0115	Effects of Adhesive Materials on Corner/Edge Bond for Automotive SiP Applications...84	Kuo-Hua Hsieh	Wistron NeWeb Corporation
TW0032	Predict the Reliability Life of Wafer Level Packaging using K-Nearest Neighbors algorithm with Cluster Analysis...88	Hung-Lin Chen	National Tsing Hua University

SESSION: Advanced Materials, Automatic Process & Assembly
Time: 15:40-17:40, Thursday, Oct. 27, 2022
Chair: Dyi Chung Hu,Siplus
Fan-Yi Ouyang, National Tsing Hua University

Paper Code	**Topic**	**Lead Author**	**Affiliation**
TW0085	Interfacial Microstructure Evolution of Indium Jointed with Different Surface Finishes after Thermal Treatments...93	Cheng-Lun Chen	Siliconware Precision Industries Co., Ltd. (SPIL)
AS0104	Cyber-Physical System of laser micro processing for semiconductor package fabrication...97	Yohei Kobayashi	The University of Tokyo
AS0124	A Plasma Enhanced CVD Technology for Solving Issues on Sidewall Deposition in Trenches and Holes...101	Masaharu Shiratani	Kyushu University

SESSION: Test, Quality, Inspection and Reliability
Time: 15:40-17:40, Thursday, Oct. 27, 2022
Chair: Jeffrey Lee, IST
Yu-Jung Huang, I-SHOU University

Paper Code	Topic	Lead Author	Affiliation
EU0101	The impact of Sn-Oxide on the solder wetting of immersion tin and how to overcome possible solderability defects to ensure constant solder wetting performance...104	Britta Schafsteller	MKS | Atotech
TW0052	Robust and Accurate Measurement Methodology for High-speed Channel Electrical Characterization...108	Yang Hung Cheng	MPI Corporation
TW0102	Determination of Dielectric Constant and Dissipation Factor of Printed Circuit Board by Microstrip With Ring and Straight-Line Resonator Measurements...111	Chien-Chang Huang	Yuan Ze University
TW0107	Copper Surface Roughness Analysis in Numerical Morphology Algorithm for the Insertion-Loss Validation...115	Li-Chi Chang	Elite Material Co.,Ltd.

SESSION: Power Electronics
Time: 10:30-12:30, Friday, Oct. 28, 2022
Chair: Albert Wu, National Central University
Chun-Kai, Liu, ITRI

SESSION: Advanced Packaging II
Time: 10:30-12:30, Friday, Oct. 28, 2022
Chair: De-Shin, Liu, National Chengchi University
CY Yang, National Central University

Paper Code	Topic	Lead Author	Affiliation
TW0134	Firewall Design for High Quality Electroplating Redistribution Layers on 600mm Panel...134	Boyin Wu	Advanced Semiconductor Engineering, Inc.
TW0073	A 2x2 Broadband Dual-Polarized Antenna Array using AiP Techniques for 5G mmWave Beamforming Systems...137	Stanley Hsiao	Advanced Semiconductor Engineering (ASE), Inc.
TW0015	Laser Drilling & Plasma Descum Employed In The Process of Wafer-Level Chip Scale Package(WLCSP)...141	Jack Huang	E&R Engineering Coporation

SESSION: HDI, IC Substrate and FPC Technology
Time: 10:30-12:30, Friday, Oct. 28, 2022
Chair: Chi-Shiung Hsi, National United University
Irving Lee, UL

Paper Code	Topic	Lead Author	Affiliation
EU0081	Hydrogen Embrittlement Suppressors for Nickel-Free Electroless Copper Baths...147	Stefanie Manuela Bremmert	MKS | Atotech

SESSION: Advacned Design & Emerging Modeling
Time: 13:30-15:30, Friday, Oct. 28, 2022
Chair: Cadmus Yuan, Feng Chia University
Kuan-Jung Chung, National Changhua University of Education

Paper Code	Topic	Lead Author	Affiliation
TW0066	Using Extra Trees Machine Learning Algorithm to Predict the Asymmetric Warpage Geometry of Panel Level Packaging...151	Zhen Hsu	National Tsing Hua University
TW0072	Study on Gaussian Process Regression to Predict Reliability Life of Wafer Level Packaging with cluster analysis..155	Chih Yi Chang	National Tsing Hua University
TW0116	The effects of time-dependent inelastic behaviors on the debonding of Cu-polyimide interface...159	Tz-Cheng Chiu	National Cheng Kung University

SESSION: Advanced Packagng Process and Design
Time: 13:30-15:15, Friday, Oct. 28, 2022
Chair: Jenn-Ming Song, National Chung Hsing University
Chien-Lung Liang, National Taiwan University of Science and Technology

Paper Code	Topic	Lead Author	Affiliation
AS0075	Adhesion and Reliability Study of Different EMC and Pre-plated Leadframe Surface Combination for Au and Cu wire bonded Leadless Package...163	April Joy Garete	Nexperia
AS0025	Effect of Package Singulation Parameters on Dual Flat Non-leaded Package Delamination...167	Siying Wu	Nexperia

SESSION: Advanced Substrate/PCB Process and Manufacturing
Time: 13:30-15:30, Friday, Oct. 28, 2022
Chair: Shu Huang, ITRI
John Liu, TPCA

Paper Code	Topic	Lead Author	Affiliation
US0016	RDL Copper Plating Process for Panel Level Packaging Application...171	Kesheng Feng	MacDermidAlpha Inc
AS0033	Printed Circuit Board (PCB) Routing Optimization with an Innovative Edge Connector for PCI-Express 5.0 and Beyond...175	huafang ju	Intel China Ltd.

Poster session-Packaging

Time: 15:10-15:40, Wednesday, October 26, 2022
Chair: Hung-Yin Tsai, Dean, National Tsing Hua University
Hsien-Chie Cheng, Distinguished Professor, Feng Chia University
Lih Shan Chen, Professor, I-SHOU University

Paper Code	Topic	Lead Author	Affiliation
TW0002	Real time analysis for Laser drilling vias of 5G Material with Multiphoton microscopy...179	Hsin Yu Chang	ITRI
TW0012	PCIe-Express Channel Design Optimization for Out-of-Guideline Three Connector Topology...181	Mark Wang	Intel
TW0034	STUDY OF HIGH-TECH FACTORY DIGITAL TWIN VIRTUAL SIMULATION MODEL BASED ON INHERENTLY SAFER DESIGN STRATEGY...185	Chang Kuo-chi	Fujian University of Technology
TW0039	The Study of the Influence on Heat Dissipation Effectiveness of the Pin-Fin Angle and Spacing in a Liquid Cooling Module...189	WU RUO-YU	T-Global Technology
TW0045	Impedance Implementation Pattern for PCB Design...194	Gary Tsai	INTEL
TW0046	Enhanced System Level Channel Characterization Methodology with Seamless Correlation among Hardware, Signal Integrity and Electrical Validation for Design Robustness...197	Jimmy Hsu	Intel
AS0057	Board Design Architecture and Optimization for High-power 48V Voltage Regulator...201	Shijuan Qin	Intel
TW0068	Pre-fabricated High-density TSV Interposer for Programmable IC Applications...205	Tsung Yu Ou Yang	ITRI
TW0088	Measurement of Laser Drilling Shift for Opaque Build-up Film by Infrared Microscope...209	Chung-Yu Ke	SPIL
AS0091	Ultrasonic dispersion of nanocomposite solder for microelectronic packaging...211	Sri Harini Rajendran	University of Seoul
TW0108	Equivalent Circuit Extraction of Solder Bumps Using a Single Calibration Component for Millimeter-Wave Packaging Applications...215	Liang-Yu Ou Yang	National Central University
TW0109	Establish a Rule for the selection of ion residue testing machines for different ion pollution sources...217	Shih Ping Chang	Siliconware Precision Industries Co.
TW0118	Optimization fingerprint reconstruction using deep learning algorithm...221	Hsiang-Chen Hsu	I-Shou University
TW0120	A Study of JEDEC Board-Level Drop Test Performance Prediction Trend of BGA Package with SAC1205 Under Different Key Factors...224	Cheng ChiMin	ASE
TW0122	Multi-Chiplet Placement Design for 3D Integration...228	Yu-Jung Huang	I-Shou University

Poster session-PCB

Time: 15:10-15:40, Thursday, October 27,2022
Chair: John Liu, Consultant, TPCA

Paper Code	Topic	Lead Author	Affiliation
AS0009	Root Cause Analysis on the FCCL Delamination of Rigid Flexible Board...232	CHENXI XIE	Shanghai Hesai Technology Co., Ltd
AS0010	Research on the Thermal Cycle Test Performance Improving in Automotive R-F PCB...235	CHENXI XIE	Shanghai Hesai Technology Co., Ltd
TW0017	Minimize Bottom Termination Component Voids by Board Assembly Process & Design Optimization...238	Kevin Hong	Universal Global Scientific Industrial Co., LTD
TW0018	Solar Cell Boost Converter with Adaptive PD Controller...244	Chao-Ting Chu	CHT
TW0019	Design of Adaptive PD Controller in Digital Solar Cell Buck Converter...248	Chao-Ting Chu	CHT
TW0035	INTELLIGENT EXPLOSION-PROOF GAS MONITORING AND EARLY WARNING SYSTEM WITH SEMICONDUCTOR PLANT AS DISASTER PREVENTION TARGET...252	Chang Kuo-chi	Fujian University of Technology
TW0044	High-speed Data Center PCB Design Challenges and Findings by Intel Automatic In-board Characterization...256	Jimmy Hsu	Intel
TW0056	Fast End-to-end Channel Electrical Characterization Methodology for Design and Manufacture Quality Check...260	Tina Yang	Intel
TW0064	An Innovative Customized PCB Surface Printing for Performance Enhancement...264	Ryan Chang	Intel
TW0094	Evaluation of the Impact of Low Parasitic Losses on Power Conversion PCB Design for Bio-Power Generation...268	Hsing-Jen Lee	Kun Shan University